

1.MATERIAL:

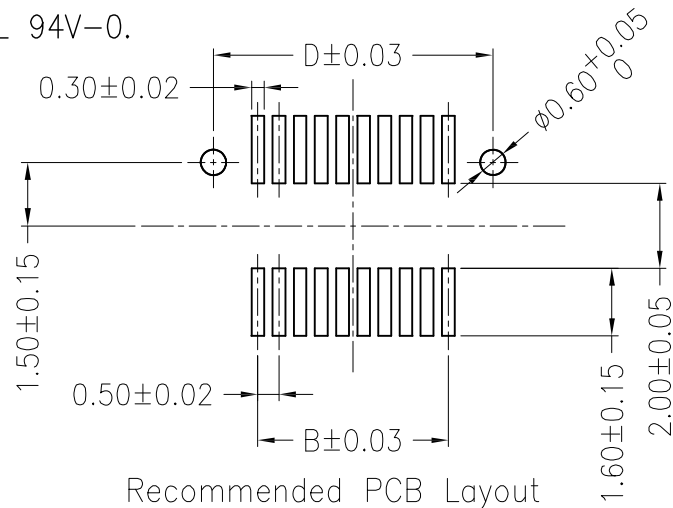
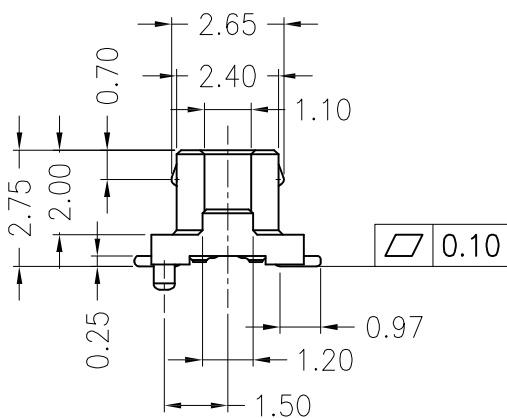
Insulator: High Temperature Thermoplastic,UL 94V-0.

Contact: Copper Alloy

2.PLATING:

Contact: 50u" Ni UnderPlating Over all

1u" Gold Plating Over all



Recommended PCB Layout

3.CODING INFORMATION:5001-BDF 0550- ** M R

PACKING:R:REEL
MALE
PIN
MATINGHEIGHT:50-5.0H

0.5BTB

JM CONN BTB CONNECTOR SERIES

CKT.	A	B	C	D
10	2.00	3.10	4.60	4.10
20	4.50	5.60	7.10	6.60
30	7.00	8.10	9.60	9.10
36	8.50	9.60	11.10	10.60
40	9.50	10.60	12.10	11.60
50	12.00	13.10	14.60	14.10
60	14.50	15.60	17.10	16.60
68	16.50	17.60	19.10	18.60
70	17.00	18.10	19.60	19.10
80	19.50	20.60	22.10	21.60

深圳市文章济美科技有限公司

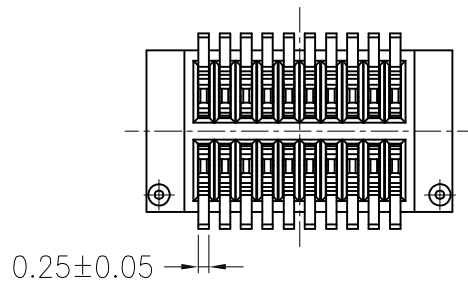
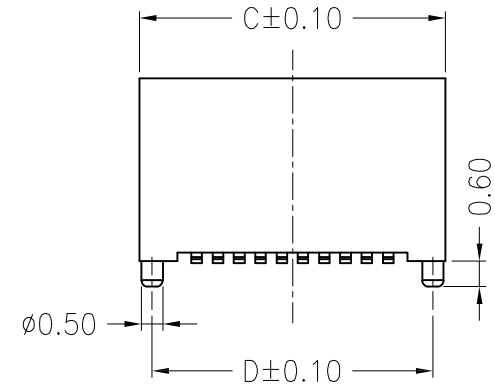
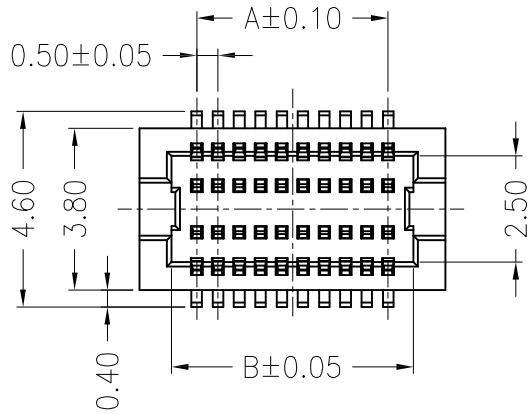
RoHS Compliant 2013/95/EC



一般公差
GENERAL TOLERANCE
.X ±0.25
.XX ±0.50
.XXX ±0.10
ANGLES ±1°

制图 (DR): Kavin 2018.09.07
品名(TITLE): 0.5BTB插座高5.0
审核 (CHKD):
料号(PART NO): 5001-BDF0550- **MR
比例(SCALE): 1:8
单位(UNITS): mm
张数(SHEET): 1 OF 1
图幅(SIZE): A4

修订 SER	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE	版本 (REV)
				A



1.MATERIAL:

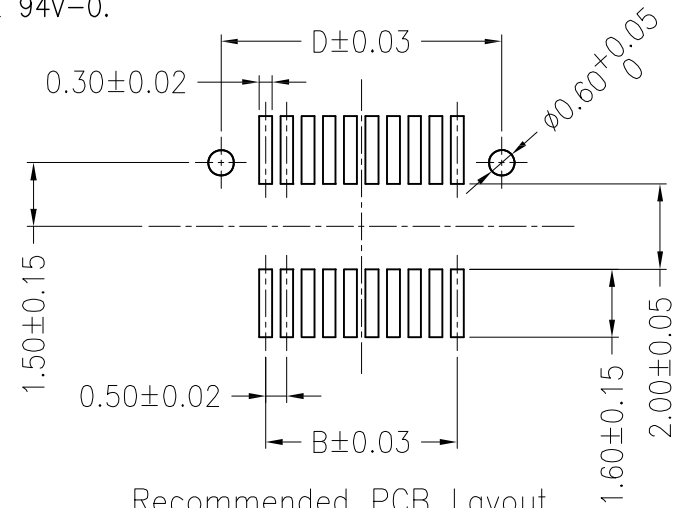
Insulator: High Temperature Thermoplastic,UL 94V-0.

Contact: Copper Alloy

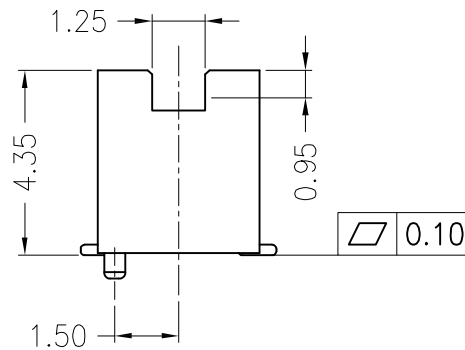
2.PLATING:

Contact: 50u" Ni UnderPlating Over all

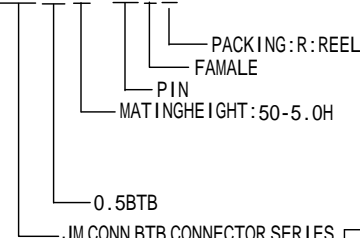
1u" Gold Plating Over all



Recommended PCB Layout



3.CODING INFORMATION:5001-BDF 0550-**FR



CKT.	A	B	C	D
10	2.00	3.20	4.70	4.10
20	4.50	5.70	7.20	6.60
30	7.00	8.20	9.70	9.10
36	8.50	9.70	11.20	10.60
40	9.50	10.70	12.20	11.60
50	12.00	13.20	14.70	14.10
60	14.50	15.70	17.20	16.60
68	16.50	17.70	19.20	18.60
70	17.00	18.20	19.70	19.10
80	19.50	20.70	22.20	21.60

深圳市文章济美科技有限公司



修订 SER	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE

版本 (REV)	
A	

一般公差 GENERAL TOLERANCE	Kevin 2018.09.07	品名(TITLE):	0.5BTB母座合高5.0		
.X ±0.25	制图 (DR):	料号(PART NO):	5001-BDF0550-**FR		
.XX ±0.20	审核 (CHKD):	比例 (SCALE)	单位 (UNITS)	张数 (SHEET)	图幅 (SIZE)
.XXX ±0.10	核准 (APPD):	1:8	mm	1 OF 1	A4
ANGLES ±1°					